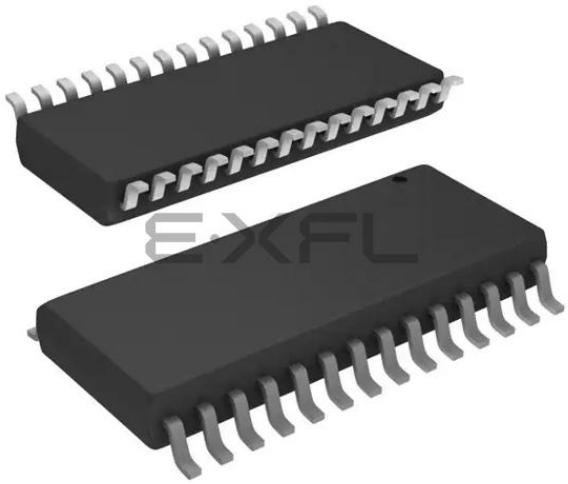
Microchip Technology - DSPIC33FJ16GS402T-I/SO Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

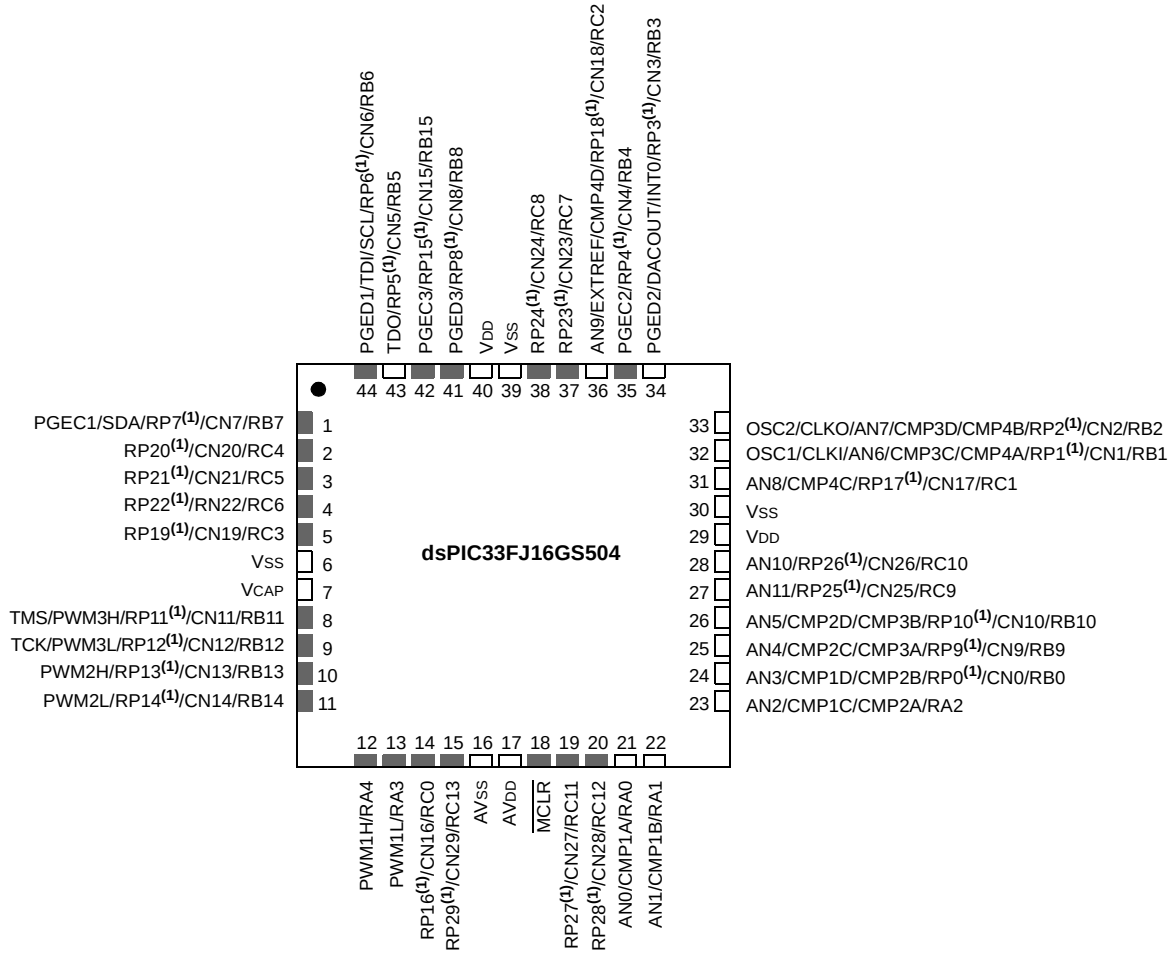
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gs402t-i-so

Pin Diagrams (Continued)

44-Pin QFN(2)

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

2.5 ICSP™ Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB® REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

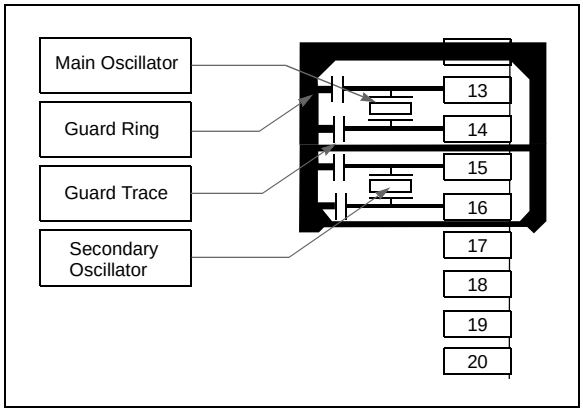
- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT

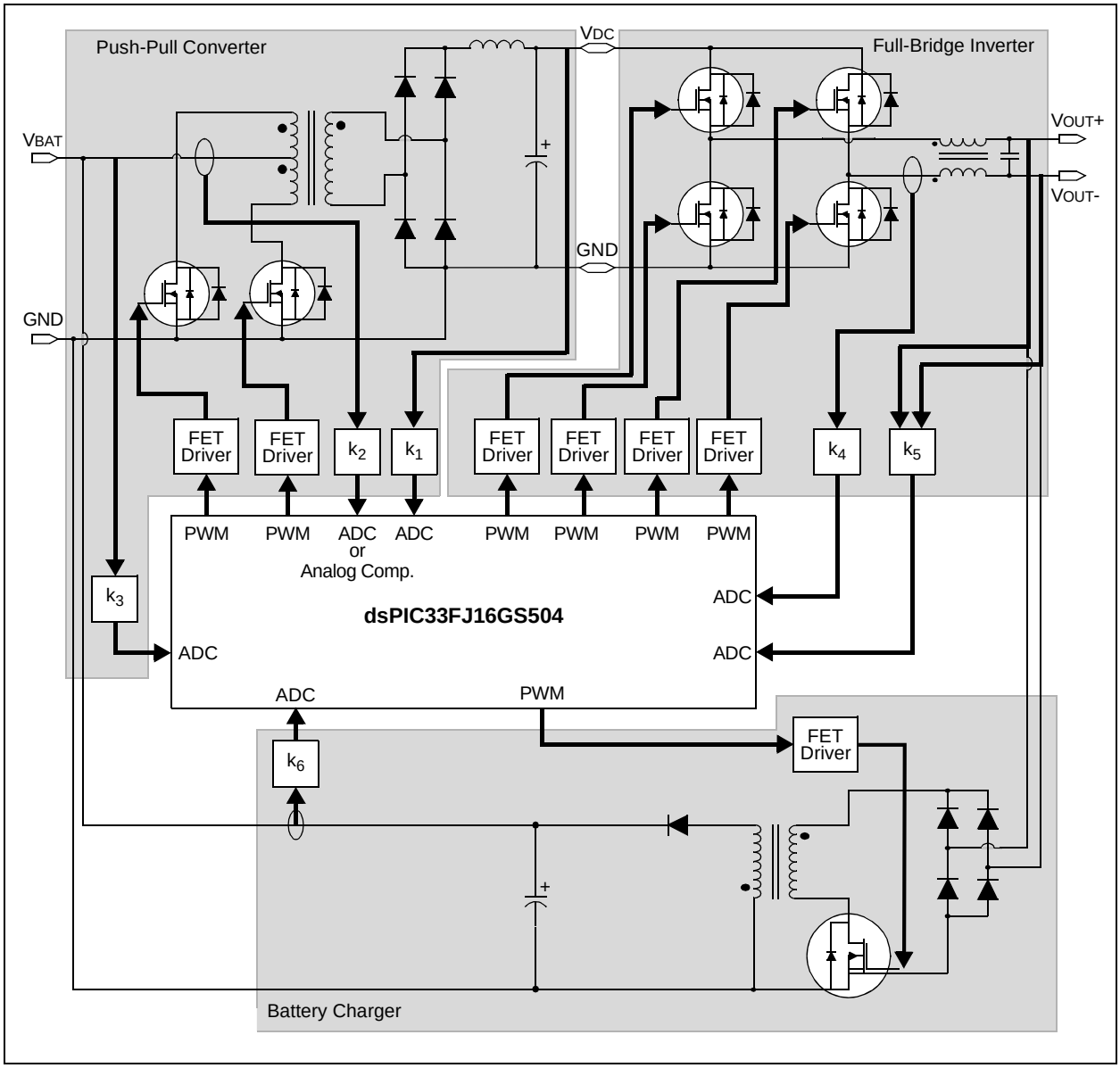


2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 4 MHz < F_{IN} < 8 MHz to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV, and PLLFBD to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration Word.

FIGURE 2-8: OFF-LINE UPS



The SAC and SAC.R instructions store either a truncated (SAC), or rounded (SAC.R) version of the contents of the target accumulator to data memory via the X bus, subject to data saturation (see **Section 3.6.3.2 "Data Space Write Saturation"**). For the MAC class of instructions, the accumulator write-back operation functions in the same manner, addressing combined MCU (X and Y) data space though the X bus. For this class of instructions, the data is always subject to rounding.

3.6.3.2 Data Space Write Saturation

In addition to adder/subtracter saturation, writes to data space can also be saturated, but without affecting the contents of the source accumulator. The data space write saturation logic block accepts a 16-bit, 1.15 fractional value from the round logic block as its input, together with overflow status from the original source (accumulator) and the 16-bit round adder. These inputs are combined and used to select the appropriate 1.15 fractional value as output to write to data space memory.

If the SATDW bit in the CORCON register is set, data (after rounding or truncation) is tested for overflow and adjusted accordingly:

- For input data greater than 0x007FFF, data written to memory is forced to the maximum positive 1.15 value, 0x7FFF.
- For input data less than 0xFF8000, data written to memory is forced to the maximum negative 1.15 value, 0x8000.

The Most Significant bit of the source (bit 39) is used to determine the sign of the operand being tested.

If the SATDW bit in the CORCON register is not set, the input data is always passed through unmodified under all conditions.

3.6.4 BARREL SHIFTER

The barrel shifter can perform up to 16-bit arithmetic or logic right shifts, or up to 16-bit left shifts in a single cycle. The source can be either of the two DSP accumulators or the X bus (to support multi-bit shifts of register or memory data).

The shifter requires a signed binary value to determine both the magnitude (number of bits) and direction of the shift operation. A positive value shifts the operand right. A negative value shifts the operand left. A value of '0' does not modify the operand.

The barrel shifter is 40 bits wide, thereby obtaining a 40-bit result for DSP shift operations and a 16-bit result for MCU shift operations. Data from the X bus is presented to the barrel shifter between bit positions 16 and 31 for right shifts, and between bit positions 0 and 16 for left shifts.

FIGURE 4-5: DATA MEMORY MAP FOR dsPIC33FJ16GS402/404/502/504 DEVICES WITH 2-KBYTE RAM

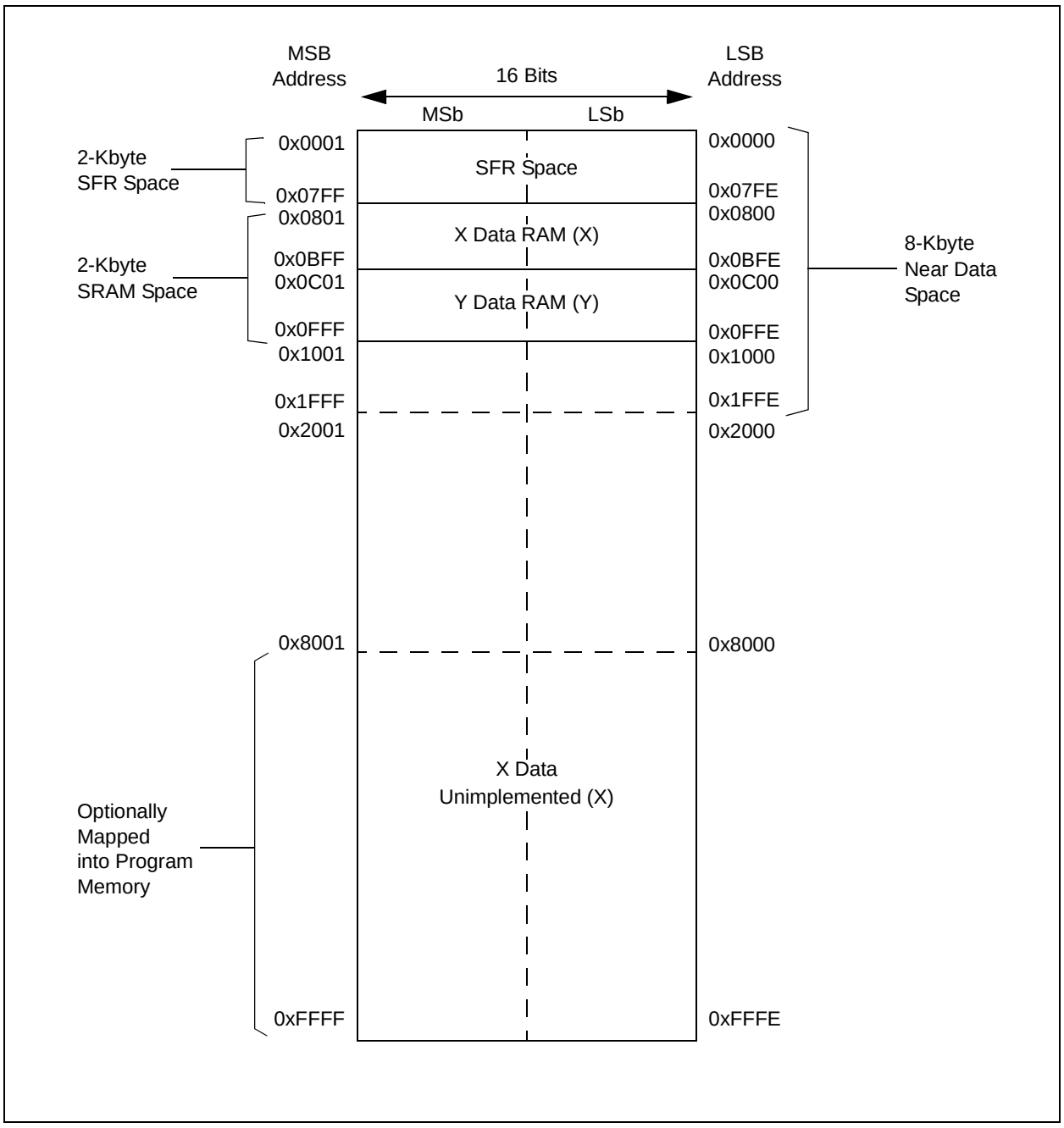


TABLE 4-18: HIGH-SPEED PWM GENERATOR 1 REGISTER MAP

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PWMCON1	0420	FLTSTAT	CLSTAT	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB	MDCS	DTC1	DTC0	—	—	—	CAM	XPRES	IUE	0000
IOCON1	0422	PENH	PENL	POLH	POLL	PMOD1	PMOD0	OVRENH	OVRENL	OVRDAT1	OVRDAT0	FLTDAT1	FLTDAT0	CLDAT1	CLDAT0	SWAP	OSYNC	0000
FCLCON1	0424	IFLTMOD	CLSRC4	CLSRC3	CLSRC2	CLSRC1	CLSRC0	CLPOL	CLMOD	FLTSRC4	FLTSRC3	FLTSRC2	FLTSRC1	FLTSRC0	FLTPOL	FLTMOD1	FLTMOD0	0000
PDC1	0426	PDC1<15:0>																0000
PHASE1	0428	PHASE1<15:0>																0000
DTR1	042A	—	—	DTR1<13:0>														0000
ALTDTR1	042C	—	—	ALTDTR1<13:0>														0000
SDC1	042E	SDC1<15:0>																0000
SPHASE1	0430	SPHASE1<15:0>																0000
TRIG1	0432	TRGCMP<15:3>													—	—	—	0000
TRGCON1	0434	TRGDIV3	TRGDIV2	TRGDIV1	TRGDIV0	—	—	—	—	DTM	—	TRGSTRT5	TRGSTRT4	TRGSTRT3	TRGSTRT2	TRGSTRT1	TRGSTRT0	0000
STRIG1	0436	STRGCMP<15:3>													—	—	—	0000
PWMCAP1	0438	PWMCAP1<15:3>													—	—	—	0000
LEBCON1	043A	PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	LEB6	LEB5	LEB4	LEB3	LEB2	LEB1	LEB0	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-19: HIGH-SPEED PWM GENERATOR 2 REGISTER MAP FOR dsPIC33FJ06GS102/202 AND dsPIC33FJ16GSX02/X04 DEVICES ONLY

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PWMCON2	0440	FLTSTAT	CLSTAT	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB	MDCS	DTC1	DTC0	—	—	—	CAM	XPRES	IUE	0000
IOCON2	0442	PENH	PENL	POLH	POLL	PMOD1	PMOD0	OVRENH	OVRENL	OVRDAT1	OVRDAT0	FLTDAT1	FLTDAT0	CLDAT1	CLDAT0	SWAP	OSYNC	0000
FCLCON2	0444	IFLTMOD	CLSRC4	CLSRC3	CLSRC2	CLSRC1	CLSRC0	CLPOL	CLMOD	FLTSRC4	FLTSRC3	FLTSRC2	FLTSRC1	FLTSRC0	FLTPOL	FLTMOD1	FLTMOD0	0000
PDC2	0446	PDC2<15:0>																0000
PHASE2	0448	PHASE2<15:0>																0000
DTR2	044A	—	—	DTR2<13:0>														0000
ALTDTR2	044C	—	—	ALTDTR2<13:0>														0000
SDC2	044E	SDC2<15:0>																0000
SPHASE2	0450	SPHASE2<15:0>																0000
TRIG2	0452	TRGCMP<15:3>													—	—	—	0000
TRGCON2	0454	TRGDIV3	TRGDIV2	TRGDIV1	TRGDIV0	—	—	—	—	DTM	—	TRGSTRT5	TRGSTRT4	TRGSTRT3	TRGSTRT2	TRGSTRT1	TRGSTRT0	0000
STRIG2	0456	STRGCMP<15:3>													—	—	—	0000
PWMCAP2	0458	PWMCAP2<15:3>													—	—	—	0000
LEBCON2	045A	PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	LEB6	LEB5	LEB4	LEB3	LEB2	LEB1	LEB0	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

8.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Oscillator (Part IV)"** (DS70307) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

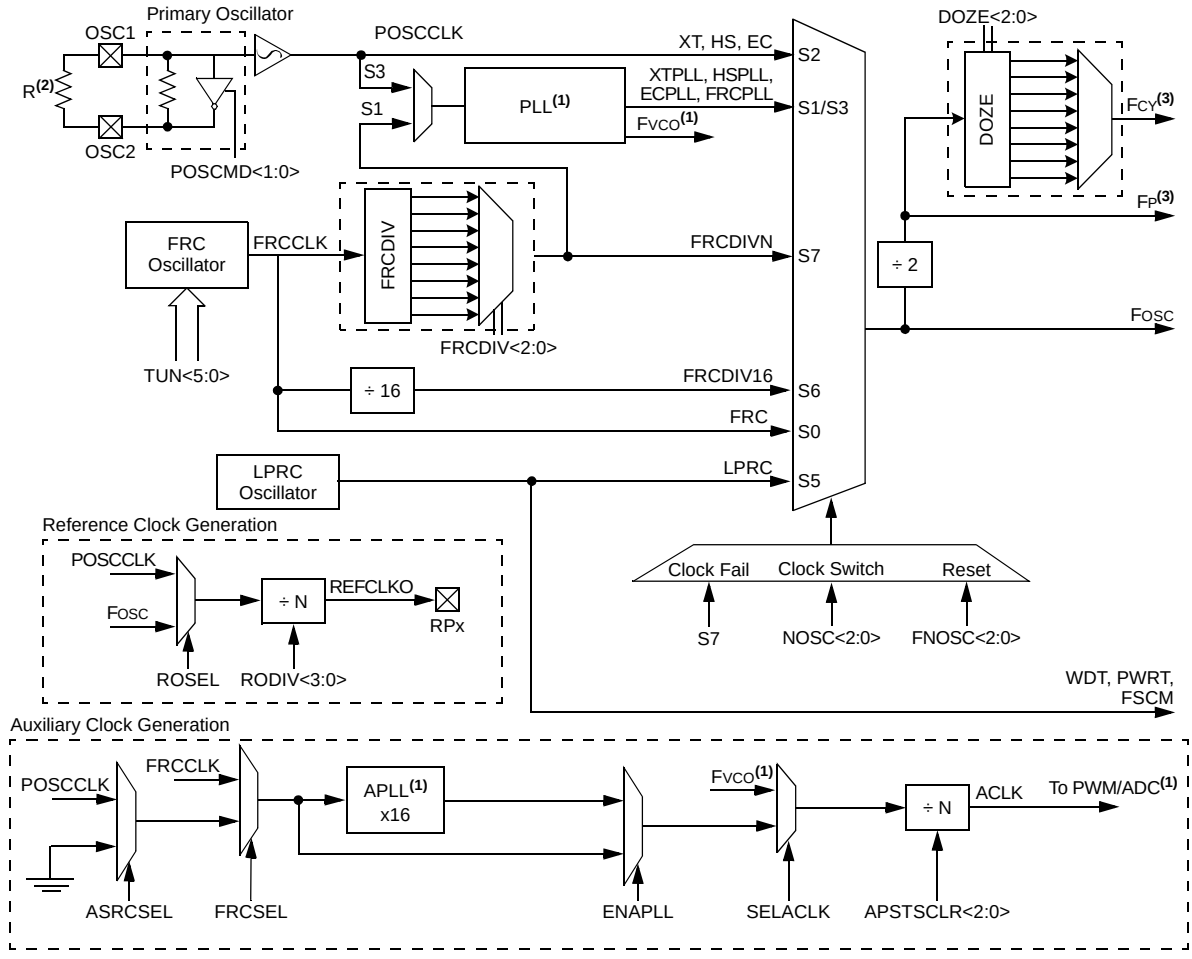
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The oscillator system provides:

- External and internal oscillator options as clock sources
- An on-chip Phase-Locked Loop (PLL) to scale the internal operating frequency to the required system clock frequency
- An internal FRC oscillator that can also be used with the PLL, thereby allowing full-speed operation without any external clock generation hardware
- Clock switching between various clock sources
- Programmable clock postscaler for system power savings
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and takes fail-safe measures
- A Clock Control register (OSCCON)
- Nonvolatile Configuration bits for main oscillator selection
- Auxiliary PLL for ADC and PWM

A simplified diagram of the oscillator system is shown in Figure 8-1.

FIGURE 8-1: OSCILLATOR SYSTEM DIAGRAM



Note 1: See **Section 8.1.3 "PLL Configuration"** and **Section 8.2 "Auxiliary Clock Generation"** for configuration restrictions.

2: If the oscillator is used with XT or HS modes, an external parallel resistor with the value of 1 MΩ must be connected.

3: The term, FP, refers to the clock source for all the peripherals, while FCY refers to the clock source for the CPU. Throughout this document, FCY and FP are used interchangeably, except in the case of Doze mode. FP and FCY will be different when Doze mode is used in any ratio other than 1:1, which is the default.

REGISTER 10-11: RPINR31: PERIPHERAL PIN SELECT INPUT REGISTER 31

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	FLT5R5	FLT5R4	FLT5R3	FLT5R2	FLT5R1	FLT5R0
bit 15							bit 8

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	FLT4R5	FLT4R4	FLT4R3	FLT4R2	FLT4R1	FLT4R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **FLT5R<5:0>:** Assign PWM Fault Input 5 (FLT5) to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **FLT4R<5:0>:** Assign PWM Fault Input 4 (FLT4) to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

REGISTER 10-13: RPINR33: PERIPHERAL PIN SELECT INPUT REGISTER 33

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	SYNCI1R5	SYNCI1R4	SYNCI1R3	SYNCI1R2	SYNCI1R1	SYNCI1R0
bit 15							bit 8

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	FLT8R5	FLT8R4	FLT8R3	FLT8R2	FLT8R1	FLT8R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **SYNCI1R<5:0>:** Assign PWM Master Time Base External Synchronization Signal to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **FLT8R<5:0>:** Assign PWM Fault Input 8 (FLT8) to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

REGISTER 10-16: RPOR1: PERIPHERAL PIN SELECT OUTPUT REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP3R5	RP3R4	RP3R3	RP3R2	RP3R1	RP3R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP2R5	RP2R4	RP2R3	RP2R2	RP2R1	RP2R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP3R<5:0>:** Peripheral Output Function is Assigned to RP3 Output Pin bits (see Table 10-2 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP2R<5:0>:** Peripheral Output Function is Assigned to RP2 Output Pin bits (see Table 10-2 for peripheral function numbers)

REGISTER 10-17: RPOR2: PERIPHERAL PIN SELECT OUTPUT REGISTER 2

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP5R5	RP5R4	RP5R3	RP5R2	RP5R1	RP5R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP4R5	RP4R4	RP4R3	RP4R2	RP4R1	RP4R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP5R<5:0>:** Peripheral Output Function is Assigned to RP5 Output Pin bits (see Table 10-2 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP4R<5:0>:** Peripheral Output Function is Assigned to RP4 Output Pin bits (see Table 10-2 for peripheral function numbers)

REGISTER 14-1: OCxCON: OUTPUT COMPARE x CONTROL REGISTER (x = 1, 2)

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	OCSIDL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0, HC	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **OCSIDL:** Stop Output Compare in Idle Mode Control bit
1 = Output Compare x halts in CPU Idle mode
0 = Output Compare x continues to operate in CPU Idle mode

bit 12-5 **Unimplemented:** Read as '0'

bit 4 **OCFLT:** PWM Fault Condition Status bit
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred (this bit is only used when OCM<2:0> = 111)

bit 3 **OCTSEL:** Output Compare Timer Select bit
1 = Timer3 is the clock source for Output Compare x
0 = Timer2 is the clock source for Output Compare x

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
111 = PWM mode on OCx, Fault pin is enabled
110 = PWM mode on OCx, Fault pin is disabled
101 = Initializes OCx pin low, generates continuous output pulses on OCx pin
100 = Initializes OCx pin low, generates single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initializes OCx pin high, compare event forces OCx pin low
001 = Initializes OCx pin low, compare event forces OCx pin high
000 = Output compare channel is disabled

REGISTER 17-1: I2CxCON: I2Cx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	U = Unimplemented bit, read as '0'		
R = Readable bit	W = Writable bit	HC = Hardware Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit
1 = Enables the I2Cx module, and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module; all I^2C™ pins are controlled by port functions.

bit 14 **Unimplemented:** Read as '0'

bit 13 **I2CSIDL:** I2Cx Stop in Idle Mode bit
1 = Discontinues module operation when device enters an Idle mode
0 = Continues module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I^2C slave)
1 = Releases SCLx clock
0 = Holds SCLx clock low (clock stretch)
If STREN = 1:
Bit is R/W (i.e., software can write '0' to initiate stretch and write '1' to release clock). Hardware clear at beginning of slave transmission. Hardware clear at end of slave reception.
If STREN = 0:
Bit is R/S (i.e., software can only write '1' to release clock). Hardware clear at beginning of slave transmission.

bit 11 **IPMIEN:** Intelligent Peripheral Management Interface (IPMI) Enable bit
1 = IPMI mode is enabled; all addresses are Acknowledged
0 = IPMI mode is disabled

bit 10 **A10M:** 10-Bit Slave Address bit
1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit
1 = Slew rate control is disabled
0 = Slew rate control is enabled

bit 8 **SMEN:** SMBus Input Levels bit
1 = Enables I/O pin thresholds compliant with SMBus specification
0 = Disables SMBus input thresholds

bit 7 **GCEN:** General Call Enable bit (when operating as I^2C slave)
1 = Enables interrupt when a general call address is received in the I2CxRSR (module is enabled for reception)
0 = General call address is disabled

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^2C slave)
Used in conjunction with the SCLREL bit.
1 = Enables software or receive clock stretching
0 = Disables software or receive clock stretching

NOTES:

REGISTER 19-1: ADCON: ANALOG-TO-DIGITAL CONTROL REGISTER (CONTINUED)

bit 4 **ASYNCSAMP:** Asynchronous Dedicated S&H Sampling Enable bit(1)

1 = The dedicated S&H is constantly sampling and then terminates sampling as soon as the trigger pulse is detected

0 = The dedicated S&H starts sampling when the trigger event is detected and completes the sampling process in two ADC clock cycles

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **ADCS<2:0>:** Analog-to-Digital Conversion Clock Divider Select bits(1)

111 = FADC/8
110 = FADC/7
101 = FADC/6
100 = FADC/5
011 = FADC/4 (default)
010 = FADC/3
001 = FADC/2
000 = FADC/1

Note 1: These control bits can only be changed while ADC is disabled (ADON = 0).

2: These bits are only available on devices with one SAR.

REGISTER 19-8: ADCPC3: ANALOG-TO-DIGITAL CONVERT PAIR CONTROL REGISTER 3(1)

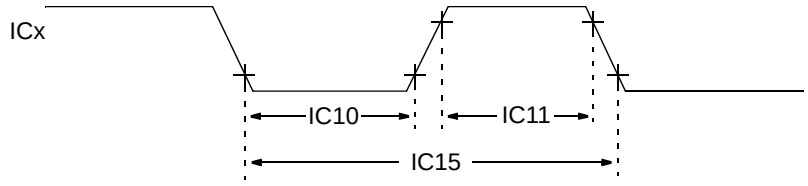
bit 4-0 **TRGSRC6<4:0>:** Trigger 6 Source Selection bits

Selects trigger source for conversion of Analog Channels AN13 and AN12.
11111 = Timer2 period match
•
•
•
11011 = Reserved
11010 = PWM Generator 4 current-limit ADC trigger
11001 = PWM Generator 3 current-limit ADC trigger
11000 = PWM Generator 2 current-limit ADC trigger
10111 = PWM Generator 1 current-limit ADC trigger
10110 = Reserved
•
•
•
10010 = Reserved
10001 = PWM Generator 4 secondary trigger is selected
10000 = PWM Generator 3 secondary trigger is selected
01111 = PWM Generator 2 secondary trigger is selected
01110 = PWM Generator 1 secondary trigger is selected
01101 = Reserved
01100 = Timer1 period match
•
•
•
01000 = Reserved
00111 = PWM Generator 4 primary trigger is selected
00110 = PWM Generator 3 primary trigger is selected
00101 = PWM Generator 2 primary trigger is selected
00100 = PWM Generator 1 primary trigger is selected
00011 = PWM Special Event Trigger is selected
00010 = Global software trigger is selected
00001 = Individual software trigger is selected
00000 = No conversion is enabled

Note 1: This register is only implemented on the dsPIC33FJ16GS502 and dsPIC33FJ16GS504 devices.

2: The trigger source must be set as global software trigger prior to setting this bit to '1'. If other conversions are in progress, conversion will be performed when the conversion resources are available.

FIGURE 24-6: INPUT CAPTURE x (ICx) TIMING CHARACTERISTICS



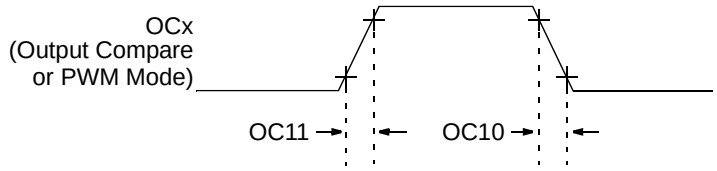
Note: Refer to Figure 24-1 for load conditions.

TABLE 24-26: INPUT CAPTURE x TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**		**Min**	**Max**	**Units**	**Conditions**
IC10	TccL	ICx Input Low Time	No prescaler	0.5 TCY + 20	—	ns	
			With prescaler	10	—	ns	
IC11	TccH	ICx Input High Time	No prescaler	0.5 TCY + 20	—	ns	
			With prescaler	10	—	ns	
IC15	TccP	ICx Input Period		(TCY + 40)/N	—	ns	N = Prescale value (1, 4, 16)

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 24-7: OUTPUT COMPARE x MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 24-1 for load conditions.

TABLE 24-27: OUTPUT COMPARE x MODULE TIMING REQUIREMENTS

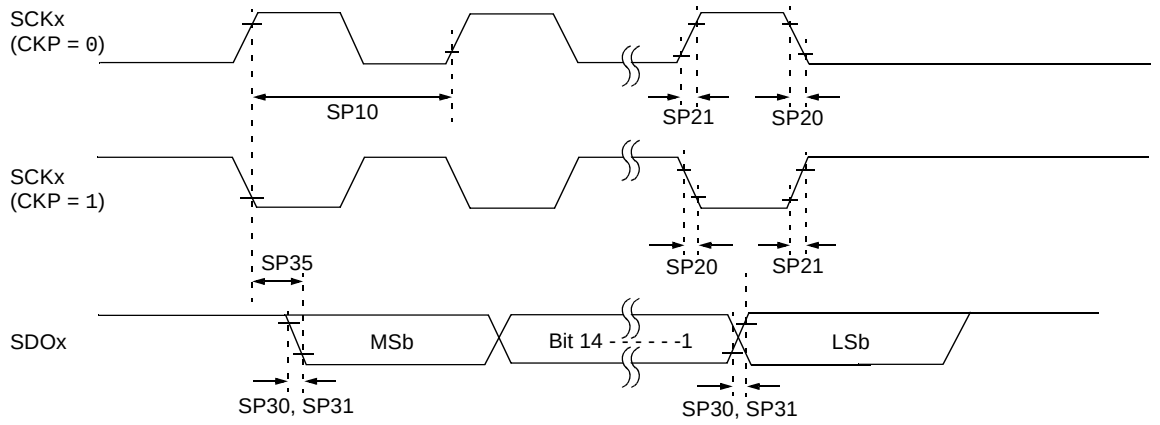
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 24-30: SPIx MAXIMUM DATA/CLOCK RATE SUMMARY

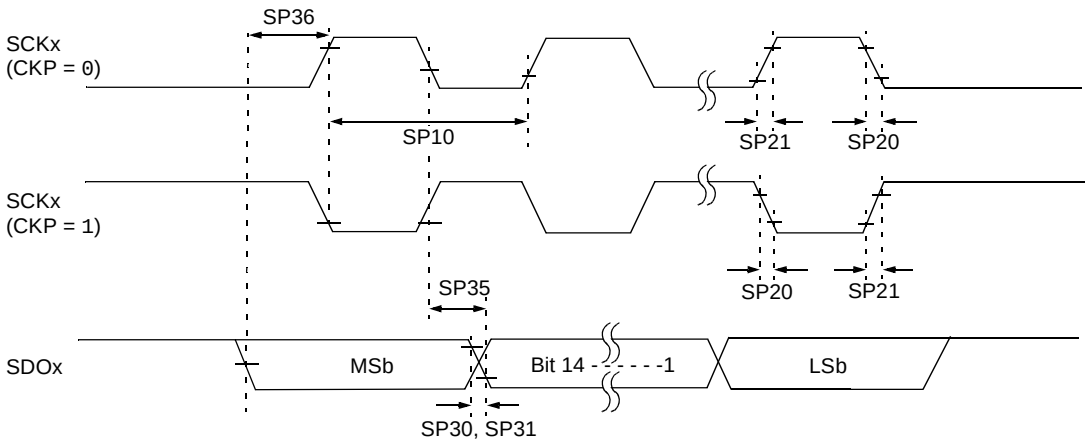
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 24-31	—	—	0,1	0,1	0,1
9 MHz	—	Table 24-32	—	1	0,1	1
9 MHz	—	Table 24-33	—	0	0,1	1
15 MHz	—	—	Table 24-34	1	0	0
11 MHz	—	—	Table 24-35	1	1	0
15 MHz	—	—	Table 24-36	0	1	0
11 MHz	—	—	Table 24-37	0	0	0

FIGURE 24-11: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 24-1 for load conditions.

FIGURE 24-12: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 24-1 for load conditions.

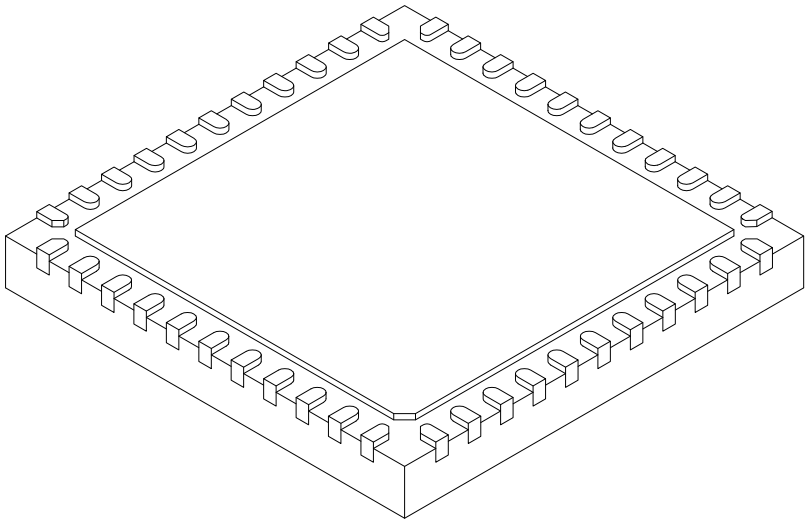
TABLE 24-44: DAC OUTPUT BUFFER DC SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 3.0V to 3.6V Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Comments**
DA10	RLOAD	Resistive Output Load Impedance	3K	—	—	Ω	
DA11	CLOAD	Output Load Capacitance	—	20	35	pF	
DA12	IOUT	Output Current Drive Strength	-1740	±1400	+1770	μA	Sink and source
DA13	VRANGE	Full Output Drive Strength Voltage Range	AVSS + 250 mV	—	AVDD – 900 mV	V	
DA14	VLRANGE	Output Drive Voltage Range at Reduced Current Drive of 50 μA	AVSS + 50 mV	—	AVDD – 500 mV	V	
DA15	IDD	Current Consumed when Module is Enabled, High-Power Mode	369	626	948	μA	Module will always consume this current even if no load is connected to the output
DA16	ROUTON	Output Impedance when Module is Enabled	—	1200	—	Ω	

Note 1: Module is functional at VBOR < VDD < VDDMIN, but with degraded performance. Module functionality is tested but not characterized.

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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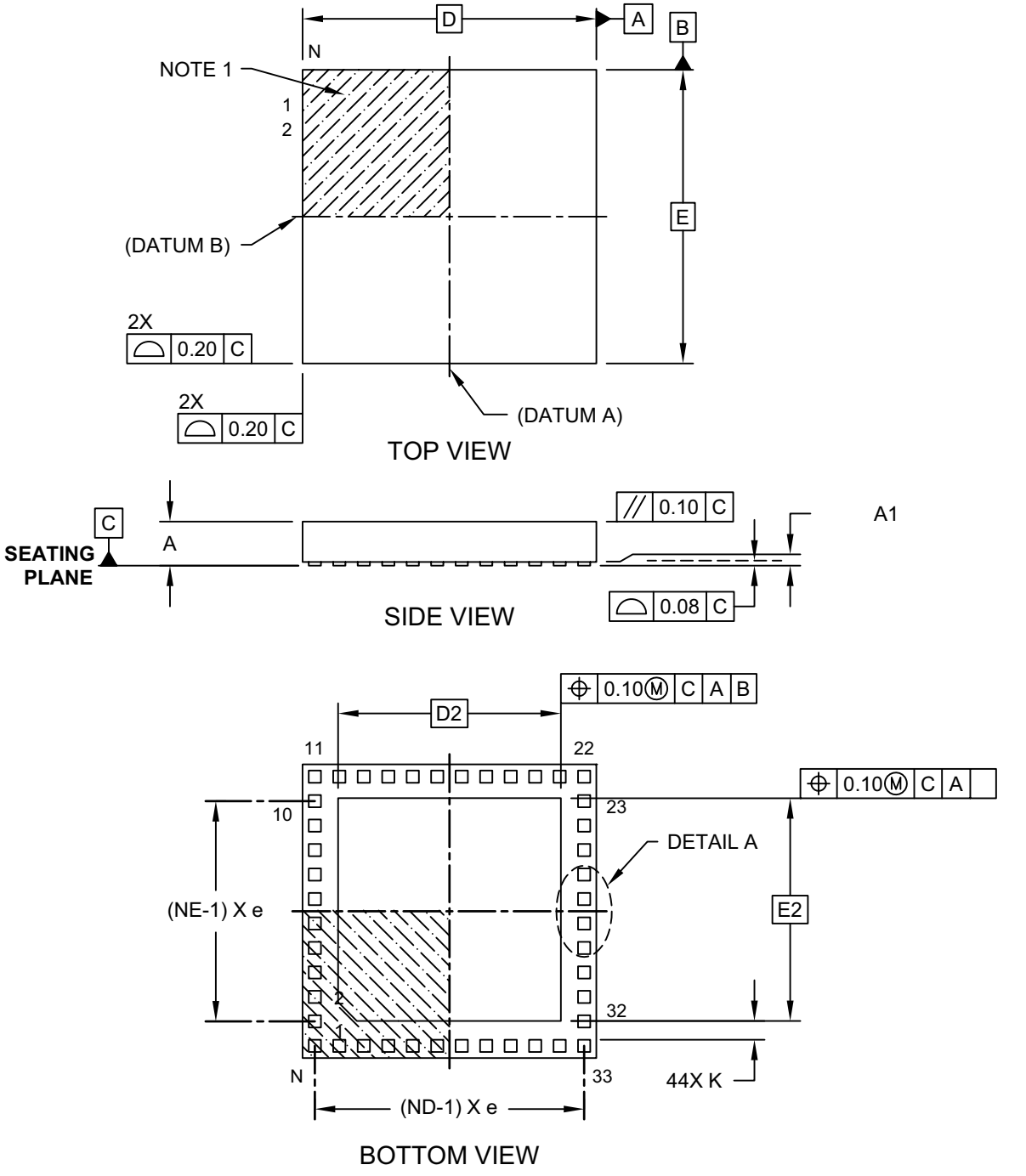
44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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